

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT3829852

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MICRON TECHNOLOGY, INC.	12/23/2009
RECEIVING PARTY DATA	
Name:	ROUND ROCK RESEARCH, LLC
Street Address:	2001 ROUTE 46
Internal Address:	WATERVIEW PLAZA, SUITE 310
City:	PARSIPPANY
State/Country:	NEW JERSEY
Postal Code:	07054
PROPERTY NUMBERS Total: 1	
Property Type	Number
Patent Number:	7094131
CORRESPONDENCE DATA	
Fax Number:	(908)654-7866
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	(908) 518-6392
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Correspondent Name:	LDLK&M
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ATTORNEY DOCKET NUMBER:	ROUND 3.0-075 CIP I
NAME OF SUBMITTER:	MELINDA C. CORMIER
SIGNATURE:	/Melinda C. Cormier/
DATE SIGNED:	04/14/2016
Total Attachments: 5	
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EXHIBIT A**CONFIRMATORY ASSIGNMENT OF PATENT RIGHTS**

This Confirmatory Assignment of Patent Rights (the "Agreement") is entered into this 30th day of December, 2009 (the "Closing Date"), by and between Micron Technology, Inc., a Delaware corporation ("Assignor"), and Round Rock Research, LLC, a Delaware limited liability company ("Assignee").

WHEREAS, Assignor and Assignee are party to that certain Patent Sale and Transfer Agreement dated on or about the date hereof (as in effect from time to time, the "Patent Sale and Transfer Agreement"); capitalized terms used but not otherwise defined in this Agreement shall have the respective meaning assigned thereto in the Patent Sale and Transfer Agreement;

WHEREAS, pursuant to the Patent Sale and Transfer Agreement, Assignor has agreed to sell, convey, transfer, assign and deliver to Assignee all of Assignor's (and its Subsidiaries') right, title and interest, including Patent Rights, in and to the Patents listed on Schedule A hereto (collectively, the "Assigned Patents");

WHEREAS, Assignee is now desirous of acquiring the entire and exclusive right, title and interest in and to the Assigned Patents in the United States and throughout the world; and

WHEREAS, Assignor is now willing to assign to Assignee all rights, title and interest in and to the Assigned Patents in the United States and throughout the world; and

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor hereby assigns, transfers and conveys to Assignee, its successors, legal representatives and assigns, and Assignee hereby accepts, all of Assignor's right, title and interest in the United States and throughout the world in and to the Assigned Patents and any and all Letters Patent that are or may be granted thereon, and any legal equivalent thereof that may be granted in any country or countries foreign to the United States, in each case including without limitation any extensions, substitutes, continuations, continuations-in-part, divisions, reissues, reexaminations, and renewals thereof, or other equivalents thereof, and further, all rights and privileges pertaining to the Assigned Patents and any and all Letters Patent that are or may be granted thereon, and any legal equivalent thereof that may be granted in any country or countries foreign to the United States, including, without limitation, the right, if any, to petition, sue or otherwise seek and recover damages, profits and any other remedy (monetary, injunctive, declaratory or other) in the United States and anywhere throughout the world for any past, present and future infringement thereof, conversion or misappropriation of, or other injury, offense, violation, breach of duty or wrong relating to, any of the Assigned Patents, or any license, agreement, contract or other matter relating thereto.

Assignor hereby authorizes and requests the Commissioner of Patents and Trademarks of the United States of America and the appropriate officers of all other jurisdictions in which the Assigned Patents are or may be registered or in which applications included among the Assigned Patents are pending, to record the title of Assignee, its successors, legal representatives and assigns, as owner of all right, title and interest in and to the Assigned Patents, and to issue to Assignee, its successors, legal representatives and assigns, all Letters Patent and any legal

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equivalent thereof that may be granted in any country or countries foreign to the United States and recordings of patent rights resulting from any application included among the Assigned Patents, in accordance with the terms of this instrument.

Except to the extent that federal law preempts state law with respect to the matters covered hereby, this Agreement shall be governed by and construed in accordance with the laws of the State of Delaware, without giving effect to any of the principles of conflicts of laws thereof that would result in the application of the laws of another jurisdiction to this Agreement.

This Agreement shall be binding on, and shall inure to the benefit of, the parties hereto and their respective successors and assigns, and may be executed in two or more counterparts, each of which shall be deemed to be an original, but all of which shall constitute one and the same agreement. Each of the parties hereto agrees to accept and be bound by facsimile signatures hereto.

Each party represents that it has taken all necessary action to authorize the execution and delivery of this Agreement.

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IN WITNESS WHEREOF, the parties hereto have caused this Agreement to be executed by their respective duly authorized officers, as of the date first written above.

ASSIGNOR:

MICRON TECHNOLOGY, INC.

By: [Signature]
Name: Stewart W. Appleton
Title: Chairman and CEO

ASSIGNEE:

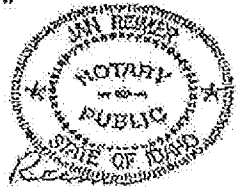
ROUND ROCK RESEARCH, LLC

By: [Signature]
Name: John Desmarais
Title: Manager

On this 23rd day of December, 2009, before me appeared Stewart W. Appleton, the person who signed this instrument, who acknowledged that he/she signed it as a free act on his/her own behalf or on behalf of the Assignor with authority to do so.

State of IDAHO)
)
County of Ada)

ss.



[Note that federal patent assignments must also include a cover sheet. See 37 C.F.R. 3.28]

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SCHEDULE A

(to be attached)

Schedule A Patents

2002-0404.00/JP	JP	27-Aug-03	METHODS AND APPARATUS FOR ELECTROMECHANICALLY AND/OR ELECTROCHEMICALLY-MECHANICALLY REMOVING CONDUCTIVE MATERIAL FROM A MICROELECTRONIC SUBSTRATE	Issued	10-Jul-09 4340233	2004-531965
2002-0404.00/KR	KR	28-Feb-05	METHODS AND APPARATUS FOR ELECTROMECHANICALLY AND/OR ELECTROCHEMICALLY-MECHANICALLY REMOVING CONDUCTIVE MATERIAL FROM A MICROELECTRONIC SUBSTRATE	Issued	10-15-Jun-07 0730900	10-2005-7003569
2002-0404.00/SG	SG	28-Feb-05	METHODS AND APPARATUS FOR ELECTROMECHANICALLY AND/OR ELECTROCHEMICALLY-MECHANICALLY REMOVING CONDUCTIVE MATERIAL FROM A MICROELECTRONIC SUBSTRATE	Issued	31-Oct-08 110648	200501182-0
2002-0404.00/UK	GB	27-Aug-03	METHODS AND APPARATUS FOR ELECTROMECHANICALLY AND/OR ELECTROCHEMICALLY-MECHANICALLY REMOVING CONDUCTIVE MATERIAL FROM A MICROELECTRONIC SUBSTRATE	Issued	24-Oct-07 1536919	03791962.8
2002-0404.00/US	US	29-Aug-02	METHODS AND APPARATUS FOR ELECTROMECHANICALLY AND/OR ELECTROCHEMICALLY-MECHANICALLY REMOVING CONDUCTIVE MATERIAL FROM A MICROELECTRONIC SUBSTRATE	Issued	22-May-07 7220166	10/230,970
2002-0404.01/EP	EP	15-Oct-07	METHODS AND APPARATUS FOR ELECTROMECHANICALLY AND/OR ELECTROCHEMICALLY-MECHANICALLY REMOVING CONDUCTIVE MATERIAL FROM A MICROELECTRONIC SUBSTRATE	Issued	28-Oct-09 1875987	07020164.5
2002-0404.01/GB	GB	15-Oct-07	METHODS AND APPARATUS FOR ELECTROMECHANICALLY AND/OR ELECTROCHEMICALLY-MECHANICALLY REMOVING CONDUCTIVE MATERIAL FROM A MICROELECTRONIC SUBSTRATE	Issued	28-Oct-09 1875987	07020164.5
2002-0404.01/IT	IT	15-Oct-07	METHODS AND APPARATUS FOR ELECTROMECHANICALLY AND/OR ELECTROCHEMICALLY-MECHANICALLY REMOVING CONDUCTIVE MATERIAL FROM A MICROELECTRONIC SUBSTRATE	Issued	28-Oct-09 1875987	07020164.5
2002-0404.01/US	US	27-Dec-06	METHODS AND APPARATUS FOR ELECTROMECHANICALLY AND/OR ELECTROCHEMICALLY-MECHANICALLY REMOVING CONDUCTIVE MATERIAL FROM A MICROELECTRONIC SUBSTRATE	Issued	17-Nov-09 7618528	11/616,683
2002-0404.02/US	US	17-Sep-09	METHODS AND APPARATUS FOR ELECTROMECHANICALLY AND/OR ELECTROCHEMICALLY-MECHANICALLY REMOVING CONDUCTIVE MATERIAL FROM A MICROELECTRONIC SUBSTRATE	Pending		12/561,824
2002-0405.00/US	US	29-Aug-02	METHODS AND APPARATUS FOR ELECTRICALLY DETECTING CHARACTERISTICS OF A MICROELECTRONIC SUBSTRATE AND/OR POLISHING MEDIUM	Issued	14-Nov-06 7134934	10/230,972
2002-0405.01/US	US	06-Jul-06	METHODS AND APPARATUS FOR ELECTRICALLY DETECTING CHARACTERISTICS OF A MICROELECTRONIC SUBSTRATE AND/OR POLISHING MEDIUM	Issued	14-Jul-09 7560017	11/482,586
2002-0406.00/US	US	29-Aug-02	METHODS AND APPARATUS FOR SELECTIVELY REMOVING CONDUCTIVE MATERIAL FROM A MICROELECTRONIC SUBSTRATE	Issued	26-Dec-06 7153195	10/230,973
2002-0406.01/US	US	23-Oct-08	METHODS AND APPARATUS FOR SELECTIVELY REMOVING CONDUCTIVE MATERIAL FROM A MICROELECTRONIC SUBSTRATE	Issued	20-Oct-09 7604729	11/585,740
2002-0406.02/US	US	16-Oct-09	METHODS AND APPARATUS FOR SELECTIVELY REMOVING CONDUCTIVE MATERIAL FROM A MICROELECTRONIC SUBSTRATE	Pending		12/580,941
2002-0430.00/US	US	15-Aug-02	DEPOSITION METHODS	Issued	10-May-05 6890596	10/222,304
2002-0430.01/US	US	08-Mar-05	DEPOSITION METHODS	Issued	03-Mar-09 7498057	11/075,017
2002-0440.00/US	US	20-Jun-03	SYSTEM AND METHOD FOR SELECTIVE MEMORY MODULE POWER MANAGEMENT	Issued	03-Sep-08 7428644	10/601,222